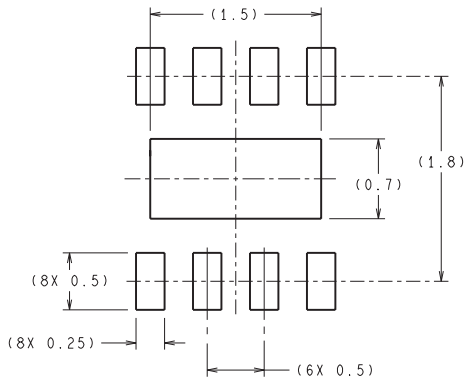
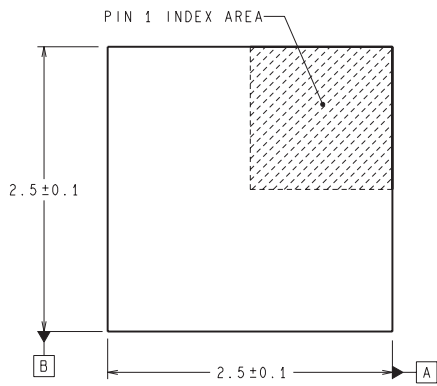


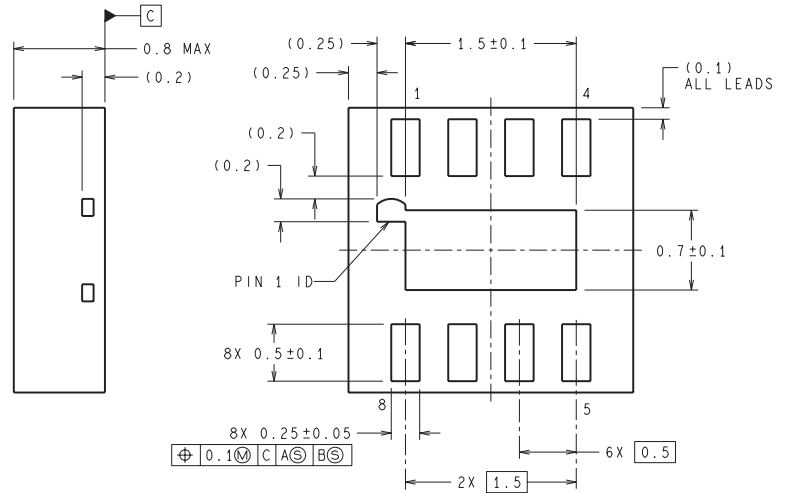
NGL0008B



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS



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LDA08B (Rev B)

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